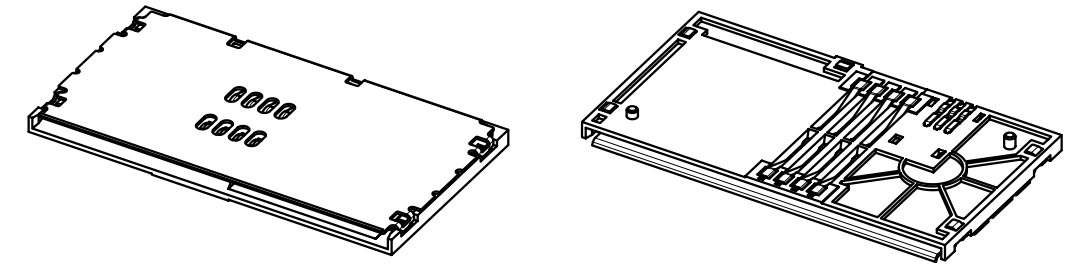
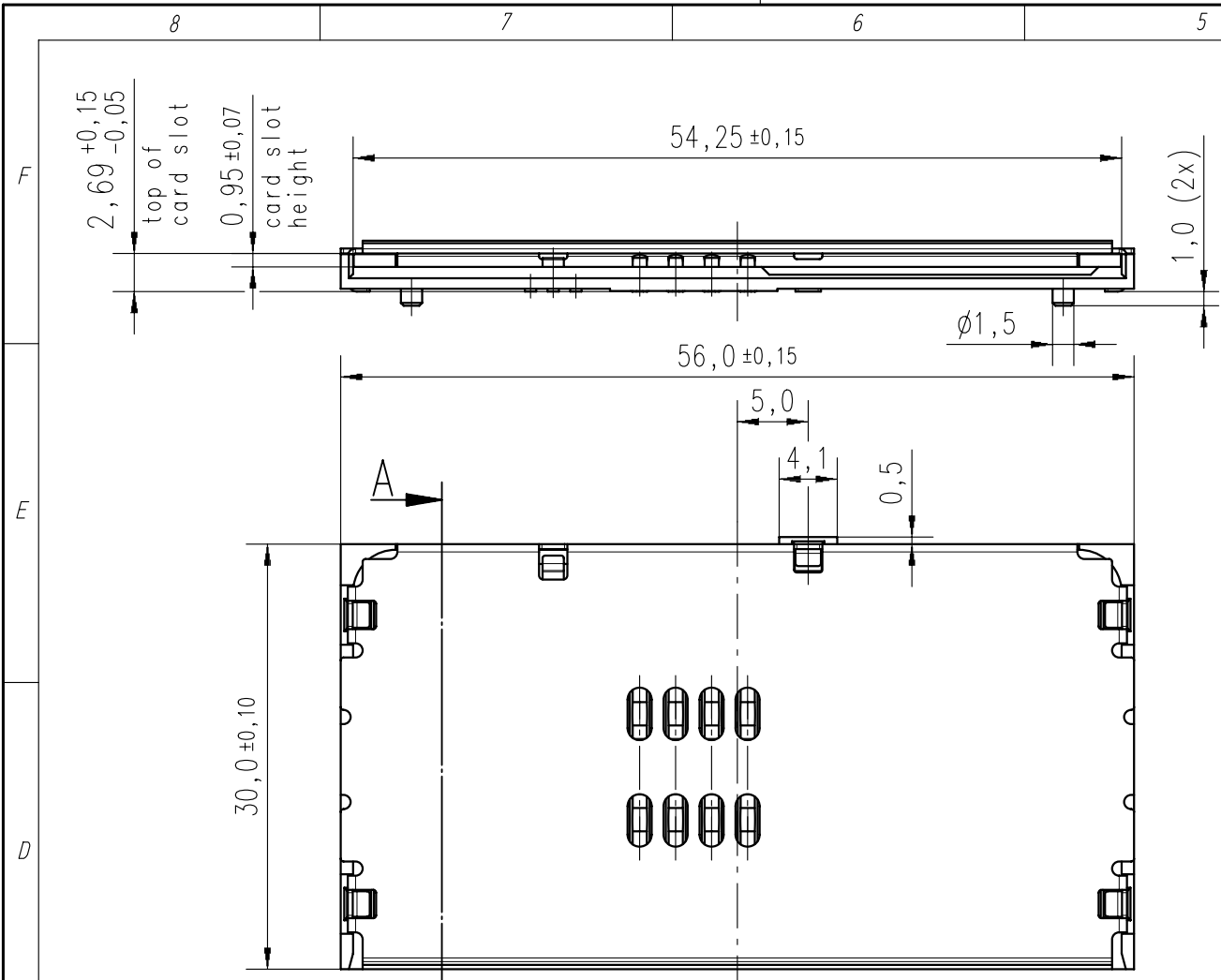
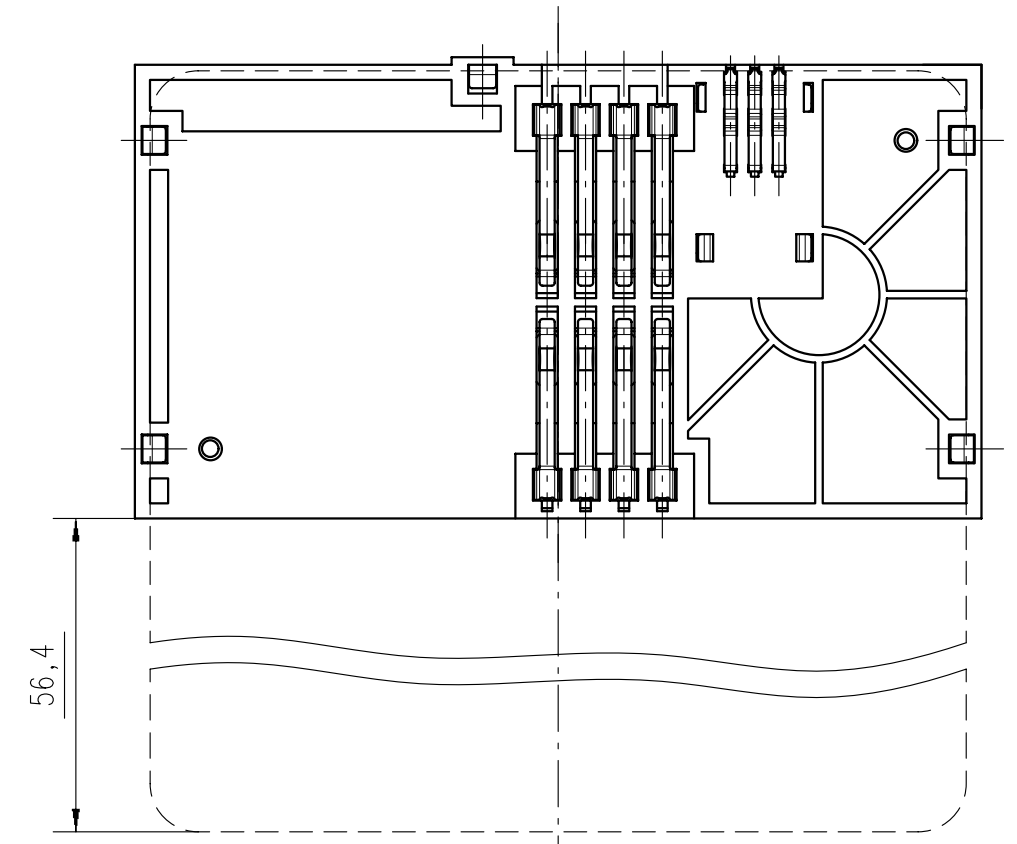
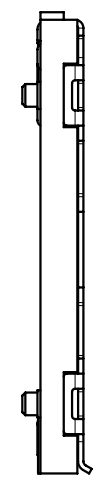


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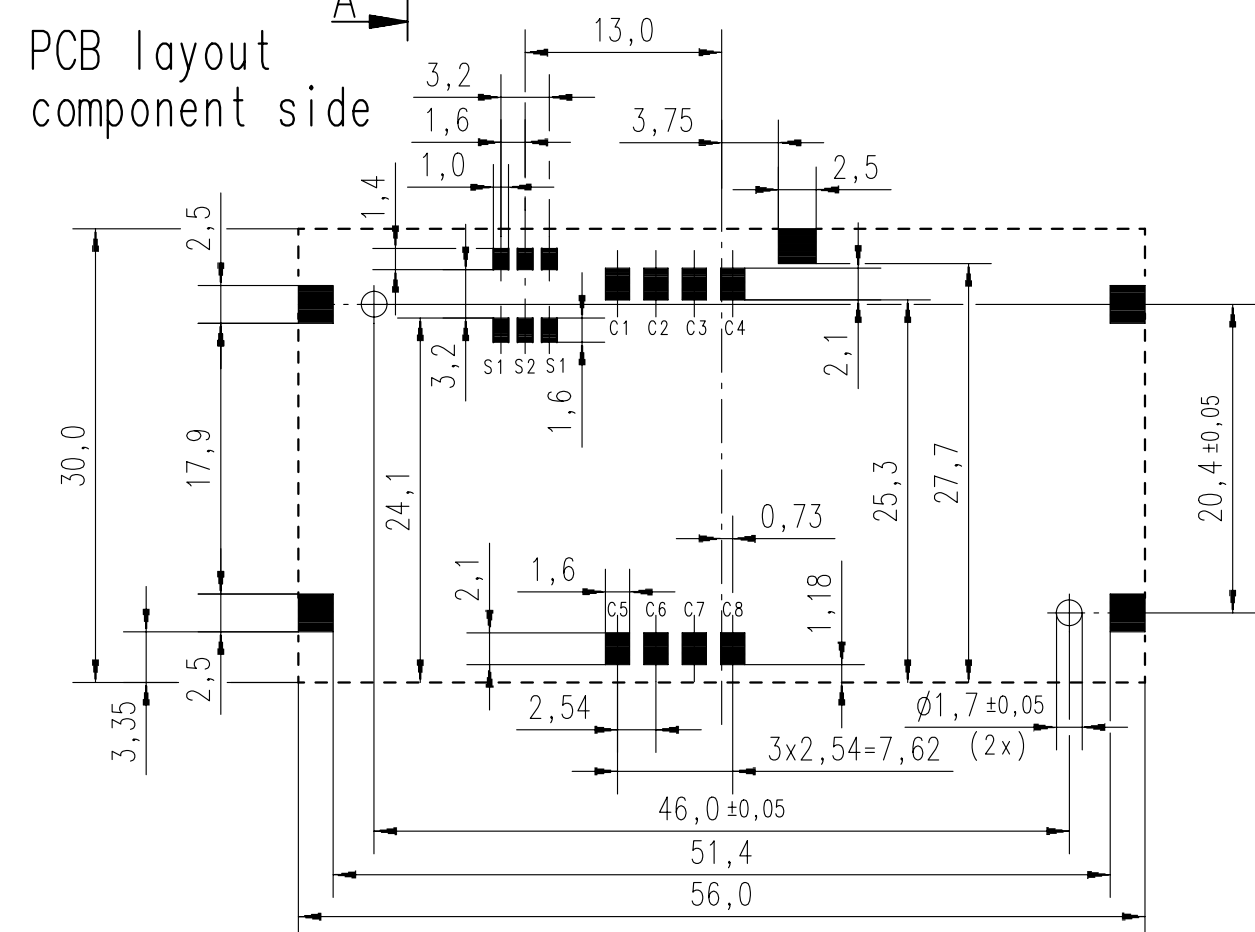
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A-A



PCB layout component side



co-planarity of solder pins \square 0,15^②
 recommended thickness of solderpaste min. 0,15 mm
 reflow solder profile see sheet 2



Im ungelöteten Zustand keine Karte stecken^②
 Don't insert a card in unsoldered condition

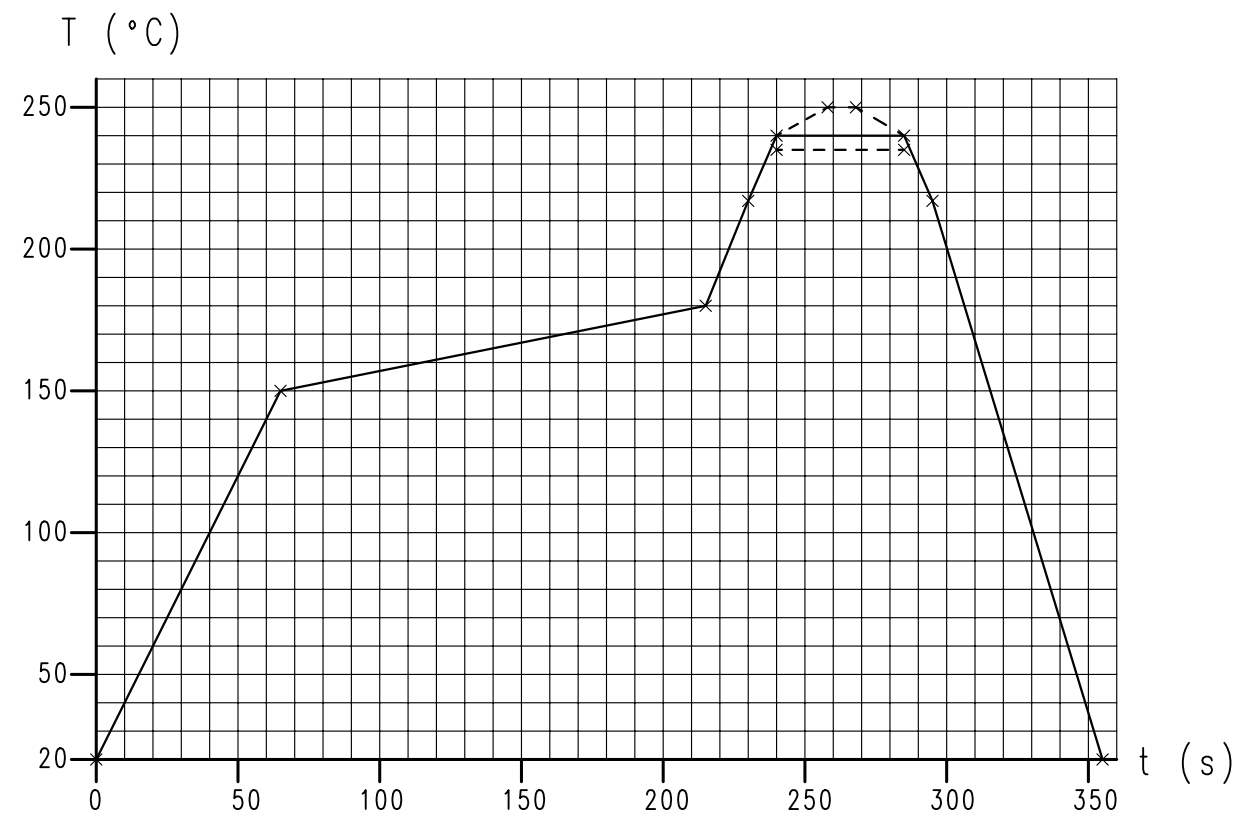
Gewicht (errechnet) / Calc WT: 7,8 9		Zul. Abw. / Tolerances:		Maßstab / Scale 2:1		A3	
Prüfmaß / Testdimension		ISO 2768-mH		DIN 6784		CUSTOMER DRAWING	
Teileindex Partindexnumber		06		Datum / Date 20.09.		Name Bertsch	
		Gez. / Drawn				Smart Card Connector	
		Gepr. / Checked				SMT with normally open switch	
		Amphenol-Tuchel Electronics GmbH		M		C702 10M008 252 40	
Index		Änderung / Description		Datum / Date		Name	
02		200700425		21.06.07		Ber.	
01		200600185		20.09.06		Ber.	
Ers. f. / Similar to:						Blatt / Sheet 1	
						2 Bl.	

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temperature profile for lead free soldering ⁰²

Sn (3,0-4,0)Ag (0,5-0,9)Cu solder alloy
 temperature measured on solderable termination



Parameter	Specification
Average temperature gradient in preheating	2,5 °C/s
Preheating temperature	150 °C - 200 °C
Soak time	120 s - 180 s
Time above 217 °C	40 s - 120 s
Peak temperature in reflow	235 °C - 250 °C
Time at peak temperature	10 s - 50 s
Temperature gradient in cooling	max -5 °C/s

Specification ⁰²

- DESIGN**
 type: push-pull, wiping contacts
 normally open switch
 with positioning studs
- GENERAL CHARACTERISTICS**
 number of contacts: 8 contacts
 switch: normally open (no card inserted)
 card type: according to ISO 7810 / 7816
 card thickness: 0,76 ±0,08 mm
 termination: SMT
- MATERIALS AND PLATING**
 insulator: LCP, black
 contact plating: Au over Ni
- CLIMATIC CHARACTERISTICS**
 operating temperature: -25 °C to +70 °C
 storage temperature: -40 °C to +85 °C
 soldering process: reflow soldering
- ELECTRICAL CHARACTERISTICS**
 contact resistance: max. 100 mΩ (data contacts)
 max. 1 Ω (switch)
 insulation resistance: >10⁹ Ω
 high voltage resistance: 500 V AC for 1 minute
 rated voltage: <15 V DC
 rated current: <1 A
- MECHANICAL CHARACTERISTICS**
 card insertion force: <10 N
 card extraction force: >1 N
 mechanical lifetime: 100.000 mating cycles
 (without corrosion stress)
- PACKAGING**
 packaging: 32 parts per tray
 24 trays per carton

Gewicht (errechnet) / Calc WT: 7,8 g		Zul. Abw. / Tolerances:		Maßstab / Scale 2:1		A3			
Prüfmaß / Testdimension		ISO 2768-mH				CUSTOMER DRAWING			
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02 200700425 21.06.07 Ber.		Amphenol-Tuchel						Blatt / Sheet	
01 200600185 20.09.06 Ber.		Electronics GmbH						2	
Index Änderung / Description Datum / Date Name								2 Bl.	
								Ers. f. / Similar to:	